WHAT IS CLAIMED IS:

1. A configuring apparatus for a thermal conductive plate, comprising:

a working platform, including a positioning seat thereon to receive the thermal conductive plate therein;

a first laminating unit, mounted to the working platform at one side of the positioning seat;

a second laminating unit, mounted to the working platform at the other side of the positioning seat; and

a moveable fusion, mounted to the working platform over the positioning seat;

wherein the first and second laminating units sequentially press the thermal conductive plate on the positioning seat allowing the fusion head to perform sealing operation thereon.

2. The apparatus of Claim 1, further comprising a heat circulating and dissipation system under the working platform, and the positioning seat is fabricated from thermal conductive material.

3. The apparatus structure of Claim 2, wherein the thermal conductive material includes copper.

4. The apparatus structure of Claim 1, wherein the positioning seat includes a recessed slot for receiving the thermal conductive plate therein.

5. The apparatus of Claim 4, wherein the positioning seat includes a moving unit underneath the recessed slot to push the thermal conductive plate upwardly over the recessed slot.

6. The apparatus of Claim 1, further comprising the first and second laminating units comprise a first and a second rotation seats mounted to the working platform, respectively, and a first and a second suspending arms driven by the first and second rotation seats, respectively.

7. The apparatus of Claim 6, wherein first and second laminating units further comprise a first and a second lamination members formed at free ends of the first and second suspending arms, respectively.

8. The apparatus of Claim 1, further comprising a coordinate mechanism mounting the fusion head to the working platform.

9. The apparatus of Claim 8, wherein the coordinate mechanism includes an X-axis slide track, an Y-axis slide track and a Z-axis slide track for driving the fusion head to move along X-axis, Y-axis and Z-axis.

10. The apparatus of Claim 1, further comprising an enclosure for masking the working platform, the first and second laminating units, and the moveable fusion head therein.

11. The apparatus of Claim 10, wherein the enclosure includes a transparent window.

12. A method for processing a thermal conductive plate joined individual plates, the method includes a step of high-temperature fusion performed on a joint between the individual plates.